

From: Stefan Anton [<mailto:s.anton@holtec.com>]
Sent: Wednesday, October 17, 2012 3:41 PM
To: Goshen, John
Cc: Waters, Michael; LicensingInt; Stefan Anton
Subject: Summary and action items for Monday's call

John,

Below is the documentation of the discussions and action items from Monday's (10/15/2012) call. Note that I did not mention tomorrow's call and the draft RSIs, since that was not specifically discussed Monday. I would expect that we update this on a regular basis.

Please take a look to make sure we accurately captured the status and next steps.

Participants:

- NRC- John Goshen, Michael Waters
- Holtec- Stefan Anton, Veena Gubbi, Debu Majumdar and Doug Weaver (silent participant)

HI-STORM UMAX:

- Background: Application submitted June 29 (calculation packages July 19). Awaiting Acceptance Letter.
- Discussion: RSI will be issued in the week of 10/22 for supplemental thermal information. Structural calculations are accepted and structural review is in progress. Holtec confirmed review should continue.
- Actions:
 - o NRC to send RSIs, expected week of 10/22
 - o Holtec to respond to RSI as soon as practicable possible, date TBD
 - o NRC to issue acceptance letter, date TBD

LAR 1014-8 (HI-STORM 100 LAR, initial submittal November 2009):

- Background: Editorial corrections necessary to the CoC, TS and SER currently in Adams
- Discussion: Corrected documents are being prepared. Since corrections are editorial, current versions are valid basis for cask loading.
- Actions:
 - o NRC to send corrected documents to Holtec by mid November.
 - o Non-substantive (administrative) Federal Register Notice (FRN) to be published in November. There is no public comment on this type of FRN.

LAR 1014-9 (HI-STORM 100 LAR, initial submittal September 2010):

- Background: Additional ambient temperature restriction proposed by SFST after the technical review.
- Discussion: Brief discussion on technical background. Temperature restriction will prevent various users from applying this amendment.
- Actions:
 - o NRC to schedule a telecon for a more detailed technical and licensing discussion to resolve by 10/26.
 - o FRN is being reviewed by NRC's OGC with completion anticipated by the end of November with FRN scheduled for publishing by February 2013.

LAR 1014-10 (HI-STORM 100 LAR, initial submittal March 2012):

- Background: Acceptance letter received. RAIs expected but not received yet by Holtec.
- Discussion: RAIs, thermal only, being prepared.
- Actions:
 - o NRC to provide RAIs, expected 10/24

LAR 1032-1 (HI-STORM FW LAR, initial submittal October 2011):

- Background: Second round of RAIs received August 17. Draft responses submitted September 17 (Thermal) and September 25 (Shielding). Two telecons on thermal responses.
- Discussion: NRC recommended some revisions to the draft responses (GCI calculations) during the 2nd telecon on October 12, 2012 to close the issue. Also, during that call, an upcoming draft guidance on best practice methods for CFD analyses and a publication that deals with mesh convergence were discussed for consideration in future submittals.
- Actions:
 - o Holtec to provide updated draft responses, with revised GCI calculations. Expected October 19, 2012.
 - o NRC to confirm acceptability or initiate further discussions
 - o Holtec to submit formal RAI responses

Pad Letter Response (Response to our letter on Pad Design analysis submitted 7/16/2012):

- Background: Letter on Pad Design Analysis submitted, addressing 11 issues
- Discussion: NRCs positive position on 7 out of 11 issues is being documented and will be submitted shortly, the remaining 4 issues require further discussions.
- Actions:
 - o NRC to submit Pad Letter Response, expected TBD
 - o Holtec to review letter and initiate actions/discussions on the remaining 4 items.

Stefan

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